

**2012 13th International Thermal,  
Mechanical and Multi-Physics  
Simulation and Experiments in  
Microelectronics and Microsystems**

**(EuroSimE 2012)**

**Cascais, Portugal  
16-18 April 2012**



IEEE Catalog Number: CFP12566-PRT  
ISBN: 978-1-4673-1512-8

# TABLE OF CONTENTS

<b>Advanced Mixed-Mode Bending Test: A Rapid, Inexpensive and Accurate Method for Fracture-Mechanical Interface Characterisation</b> .....	1
<i>B. Wunderle, M. Schulz, J. Keller, D. May, I. Maus, H. Pape, B. Michel</i>	
<b>An Approach to Life Consumption Monitoring of Solder Joints in Operating Temperature</b> .....	12
<i>Jonas Johansson, Ilja Belov, Erland Johnson, Peter Leisner</i>	
<b>Thermal Management for Stackable Packages with Stacked ICs</b> .....	20
<i>L. Meinshausen, K. Weide-Zaage, H. Fremont</i>	
<b>Influence of the Barrier Properties on the Mechanical Stress and Migration Distribution in a Copper Metallization</b> .....	26
<i>Jorg Kludt, J. Ciptokusumo, K. Weide-Zaage</i>	
<b>Molecularly Derived Mesoscale Modeling of an Epoxy/Cu Interface (Part III*): Interface Roughness</b> .....	31
<i>Nancy Iwamoto</i>	
<b>Comparison of Ni- and SiGe-based MEMS Magnetometers</b> .....	39
<i>V. Rochus, R. Jansen, X. Rottenberg, H. A. C. Tilmans, S. Ranvier, H. Lamy, P. Rochus</i>	
<b>PZT Piezoelectric Coefficient Extraction by PZT-actuated Micro-beam Characterization and Modeling</b> .....	46
<i>F. Casset, M. Cuff, A. Suhm, G. Le Rhun, J. Abergel, M. Allain, C. Dieppedale, T. Ricart, S. Fanget, D. Faralli, P. Ancey, A. Devos, E. Defay</i>	
<b>Evaluation of Quasi-Hermetic Packaging Solutions for Active Microwave Devices and Space Applications</b> .....	50
<i>W. Ben Naceur, N. Malbert, N. Labat, H. Fremont, J.-L. Muraro, P. Monfraix</i>	
<b>Anisotropic Strain-Field-induced Change of the Electronic Conductivity of Graphene Sheets and Carbon Nanotubes</b> .....	57
<i>Masato Ohnishi, Ken Suzuki, Hideo Miura</i>	
<b>Residual Stresses in Isotropic Conductive Adhesives with Nano-Ag Particles</b> .....	63
<i>M. Erinc, M. Van Dijk, V. G. Kouznetsova</i>	
<b>GaN Growth on Patterned Silicon Substrates. A Thermo Mechanical Study on Wafer Bow Reduction</b> .....	69
<i>Mario Gonzalez, Kai Cheng, Peter Tseng, Gustaaf Borghs</i>	
<b>Investigation of Chip Temperature Related to Various Copper Thickness on Glass-Fabric-Based Substrate</b> .....	75
<i>Jin-Ju Chue, Chih-Chyau Yang, Chen-Chia Chen, Chun-Chieh Chiu, Chien-Ming Wu</i>	
<b>Material Characterization to Model linear Viscoelastic Behavior of Thin Organic Polymer Films in Microelectronics</b> .....	81
<i>Katrin Unterhofer, Harald Preu, Jurgen Walter, Georg Lorenz, Walter Mack, Matthias Petzold</i>	
<b>Investigation on the Effect of Surface Roughness on the Fracture Strength of SCS</b> .....	89
<i>C. T. Lai, T. Y. Hung, K. N. Chiang</i>	
<b>Transient Electro-Thermal Simulation of Interconnected Systems</b> .....	95
<i>Torsten Hauck, Evgeny Rudnyi</i>	
<b>Effect of Isothermal Aging and Salt Spray Tests on Reliability and Mechanical Strength of Eutectic Sn-Bi Lead-Free Solder Joints</b> .....	99
<i>M. Mostofzadeh, J. Pippola, T. Martila, L. Frisk</i>	
<b>An Extensive Investigation of the Four Point Bending Test for Interface Characterization</b> .....	107
<i>S. P. M. Noijen, O. Van Der Sluis, P. H. M. Timmermans</i>	
<b>Shear Stress Modeling of ACA Joints in Thermal Tests</b> .....	116
<i>Kirsi Saarinen, Laura Frisk</i>	
<b>Evaluation of Very Low Bending Radius of Flexible Circuits Beyond the Standard Design Rules</b> .....	124
<i>W. C. Maia Filho, S. Hameau, M. Brizoux</i>	
<b>3-D Finite Elements Simulation of Drop Test Reliability on a Chip Scale Package: Focus on the Component Architecture and Materials</b> .....	128
<i>Soufyane Belhenini, Abdelhake Bouchou, Franck Dosseul, Abdellah Tougui</i>	
<b>Transport of Moisture at Epoxy-SiO<sub>2</sub> Interfaces Investigated by Molecular Modeling</b> .....	134
<i>O. Holck, J. Bauer, T. Braun, H. Walter, O. Wittler, B. Wunderle</i>	
<b>Numerical Modelling of Anchor Losses in MEMS Resonators</b> .....	140
<i>A. Frangi, A. Bugada, M. Martello, P. T. Savadkoohi</i>	
<b>Thermal Modeling of Active Embedded Chip into High Density Electronic Board</b> .....	148
<i>Cheikh Tidiane Dia, Eric Monier-Vinard, Valentin Bissuel, Olivier Daniel</i>	

<b>A Simplified and Meaningful Crack Propagation Model in Silicon for Microelectronic Power Devices</b> .....	157
<i>D. Calvez, F. Roqueta, S. Jacques, S. Ducret, L. Bechou, Y. Ousten</i>	
<b>A Comparison of the Creep Behaviour of Joint-Scale SAC105 and SAC305 Solder Samples under Shear Conditions</b> .....	163
<i>Cillian Burke, Jeff Punch</i>	
<b>Study of CNT Growth Termination Mechanism: Effect of Catalyst Diffusion</b> .....	173
<i>Zhaoli Gao, M. M. F. Yuen</i>	
<b>In Situ Vibration Measurements on Power Modules Under Operating Conditions</b> .....	178
<i>B. Czerny, B. Nagl, M. Lederer, A. Trnka, G. Khatibi, M. Thoben</i>	
<b>Transient Thermal Analysis as Failure Analytical Tool in Electronic Packaging</b> .....	183
<i>D. May, B. Wunderle, R. Schacht, B. Michel</i>	
<b>Testing and Multi-scale Modeling of Drop and Impact Loading of Complex MEMS Microphone Assemblies</b> .....	191
<i>J. Meng, T. Mattila, A. Dasgupta</i>	
<b>In-situ – Characterization of Moisture Induced Swelling Behaviour of Microelectronic Relevant Polymers</b> .....	199
<i>H. Walter, J. Bauer, T. Braun, O. Holck, B. Wunderle, O. Wittler</i>	
<b>Simulation of the Frequency Response of a Thermal Flow Sensor in Gaseous Media</b> .....	205
<i>Diego Fernando Reyes-Romero, Gerald Anton Urban</i>	
<b>A Novel Wafer -Level Test Method To Measure The Bond Strength In Microelectronic Materials</b> .....	212
<i>Sara Carniello, Jorg Siegert, Bernhard Loffler, Ewald Stuckler</i>	
<b>Simulations of a High Temperature Pressure Sensor Packaging and Interconnection</b> .....	216
<i>Klas Brinkfeldt, Jan Formanek, Alexander Laposa, Jiri Jakovenko, Erik Adolfsson, Per Johander</i>	
<b>Thermal Performance Evaluation of SiC Power Devices Packaging</b> .....	221
<i>A. Gracia, S. Azzopardi, E. Woirgard</i>	
<b>Accelerated Lifetime Measurements of Cu-Al ball Bonded Interconnects</b> .....	226
<i>A. Lassnig, R. Pelzer, G. Khatibi, B. Weiss, M. Nelhiebel</i>	
<b>Thermal Improvement of Die Attach with Iodine Treatment and Its Application in Solid State Lighting</b> .....	231
<i>Kai Zhang, Xinfeng Zhang, Min Zhang, Chen Yang, Hongye Sun, Matthew Yuen, Barry Zhong, Lisa Liu</i>	
<b>3D Electrostatic Microgenerator</b> .....	235
<i>Vladimir Janicek, Miroslav Husak</i>	
<b>Combined Creep and Fatigue Measurement Method for Lead-free Solder Alloys</b> .....	243
<i>R. Metasch, M. Roellig, K.-J. Wolter</i>	
<b>Cu/Epoxy Interface Enhancement and Characterization with Thiol Treatment</b> .....	250
<i>Peng He, Matthew M. F. Yuen</i>	
<b>Establishment of the Mesoscale Parameters for epoxy-copper Interfacial Separation</b> .....	259
<i>C. K. Y. Wong, S. Y. Y. Leung, R. H. Poelma, K. M. B. Jansen, C. C. A. Yuan</i>	
<b>Wettability of Organic Ferroelectric Material on Metal Substrate</b> .....	265
<i>William Hau, Guo-Dong Zhu, Nancy Iwamoto, Jun Wang, Hai-Bo Fan, Matthew M. F. Yuen</i>	
<b>Establishing the Interfacial Fracture Properties of Cu-EMC Interfaces at Harsh Condition</b> .....	270
<i>M. Sadeghinia, K. M. B. Jansen, L. J. Ernst, H. Pape</i>	
<b>Characterization of Intermetallic Compounds in Cu-Al Ball Bonds: Mechanical Properties, Delamination Strength and Thermal Conductivity</b> .....	274
<i>M. H. M. Kouters, G. H. M. Gubbels, C. A. Yuan</i>	
<b>Molecular Modeling of the Conductivity Changes of the Emeraldine Base Polyaniline Due to Protonic Acid Doping</b> .....	283
<i>Xianping Chen, Cadmus A. Yuan, Cell K. Y. Wong, Guoqi Zhang</i>	
<b>Thermo-Mechanical Investigation of the Reliability of Embedded Components in PCBs During Processing and Under Bending Loading</b> .....	287
<i>Bilim Atli-Veltin, Huang Ling, Susan Zhao, Sander Noijen, Jo Caers, Liu Weifeng, Gao Feng, Ye Yuming</i>	
<b>Experimental System for Analysing the Combined Loading And Failure Modes of Solder Joints in Electronic Packaging</b> .....	291
<i>Krystian Jankowski, Artur Wymyslowski, Didier Chicot</i>	
<b>Parameter Optimization of Torque Wireless Sensors Based on Surface Acoustic Waves (SAW)</b> .....	296
<i>Elena Zukowski, Thomas Fellner, Jürgen Wilde, Michael Berndt</i>	
<b>Thermo-mechanical Characterization and Modeling of TSV Annealing Behavior</b> .....	302
<i>P. Saettler, D. Kovalenko, K. Meier, M. Roellig, M. Boettcher, K. J. Wolter</i>	
<b>Stress Chip Measurements of the Internal Package Stress for Process Characterization and Health Monitoring</b> .....	308
<i>F. Schindler-Saefkow, F. Rost, A. Otto, W. Faust, B. Wunderle, B. Michel, S. Rzepka</i>	

<b>Viscoplastic Behavior of Diamond Die Attach Subjected to High Temperature Conditions</b> .....	318
<i>S. Msolli, A. Baazaoui, O. Dalverny, J. Alexis, M. Karama</i>	
<b>Increasing the Robustness for Reliable Packages by Prediction of Delamination by Cohesive Zone Element Simulation</b> .....	324
<i>R. Pufall, M. Goroll, W. Kanert, R. Dudek</i>	
<b>MEMS Accelerometers and their Bio-Applications</b> .....	328
<i>M. Trifunovic, W. D. Van Driel</i>	
<b>Thermal Resistance Investigations on New Leadframe-based LED Packages and Boards</b> .....	335
<i>B. Pardo, A. Gasse, A. Fargeix, J. Jakovenko, R. J. Werkhoven, X. Perpina, T. Van Weelden, P. Bancken</i>	
<b>LED Driver Thermal Design Considerations for Solid-State Lighting Technologies</b> .....	344
<i>X. Perpina, R. J. Werkhoven, M. Vellvehi, X. Jorda, J. M. G. Kunen, J. Jakovenko, P. Bancken</i>	
<b>Simulations of Thermo-Elastic Losses in a Meta-Material Bulk Bar Resonator</b> .....	349
<i>R. Jansen, X. Rottenberg, V. Rochus, H. A. C. Tilmans</i>	
<b>Optimized Design and Placement of Piezoelectric Transducers for Micromechanical Structures Subject to Membrane Stress</b> .....	354
<i>G. B. Torri, X. Rottenberg, D. M. Karabacak, M. Vandecasteele, C. Van Hoof, R. Puers</i>	
<b>Thermo-mechanical Reliability of Embedded Capacitors</b> .....	362
<i>A. Renault, C. Munier</i>	
<b>Modeling Lead Free Solder Reliability in SSL Applications Towards Virtual Design</b> .....	367
<i>Rene Kregting, Muge Erinc, Jan Kloosterman</i>	
<b>Lifetime Assessment of BGA Solder Joints with Voids under Thermo-Mechanical Load</b> .....	373
<i>Robert Schwerz, Mike Roellig, Karsten Meier, Klaus-Juergen Wolter</i>	
<b>2D Finite Elements Electro-thermal Modeling for IGBT: Uni and Multicellular Approach</b> .....	380
<i>K. El Boukkari, S. Azzopardi, L. Theolier, J. Y. Deletage, E. Woirgard</i>	
<b>Modelling of the Electric Field Assisted Capillarity Effect used for the Fabrication of Hollow Polymer Microstructures</b> .....	385
<i>C. Tonry, M. Patel, C. Bailey, M. P. Y. Desmuliez, S. Cargill, W. Yu</i>	
<b>Influence of Conversion Level on Simulation Results of Crosslinked Polymers</b> .....	391
<i>Sebastian J. Tesarski, Artur Wymyslowski, Ole Holck</i>	
<b>Thermo-mechanical Evaluation and Life Time Simulation of High Power LED Lamp Boards</b> .....	398
<i>J. Jakovenko, J. Formanek, B. Pardo, X. Perpina, R. J. Werkhoven, J. M. G. Kunen, P. Bancken, P. J. Bolt</i>	
<b>Interfacial Fracture Toughness Measurements in Microelectronic Packages with Different Test Setups on Samples From Production</b> .....	403
<i>I. Maus, H. Pape, H. S. Nabi, M. Goroll, H. Preu, J. Keller, L. J. Ernst, B. Michel, B. Wunderle</i>	
<b>Assessment of Thermo-Mechanical Stresses in Low Temperature Joining Technology</b> .....	410
<i>Thomas Herboth, Christiane Fruh, Michael Gunther, Jurgen Wilde</i>	
<b>Thermal Modelling and Optimisation of Hot Solder Dip Process</b> .....	417
<i>Stoyan Stoyanov, Chris Bailey, Peter Tollafield, Rob Crawford, Mike Parker, Jim Scott, John Roulston</i>	
<b>Reliability and Functionality Investigation of CFRP Embedded Ultrasonic Transducers Supported by FEM and EFIT Simulations</b> .....	425
<i>Mike Roellig, Frank Schubert, Georg Lautenschlaeger, Michael Franke, Bjoern Boehme, Norbert Meyendorff</i>	
<b>Modelling of Temperature Distribution in Thermal Microsensors on Sandwich Thermally Isolated Structures</b> .....	433
<i>A. G. Kozlov, D. Randjelovic</i>	
<b>Study of an Active Thermal Recovery Mechanism for an Electrostatically Actuated RF-MEMS Switch</b> .....	438
<i>T. Kuenzig, J. Iannacci, G. Schrag, G. Wachutka</i>	
<b>Experimental and Numerical Assessment of Adhesion in Real-Life MEMS</b> .....	445
<i>R. Ardito, L. Baldassarre, A. Corigliano, B. De Masi, A. Frangi, L. Magagnin</i>	
<b>Dynamic Thermal Simulation of High Brightness LEDs with Unsteady Driver Power Output</b> .....	451
<i>H. Ye, Sau Koh, J. Wei, H. W. Vanzeijl, G. Q. Zhang</i>	
<b>A Domain Decomposition Method for the Simulation of Fracture in Polysilicon MEMS</b> .....	456
<i>Federica Confalonieri, Giuseppe Cocchetti, Aldo Ghisi, Alberto Corigliano</i>	
<b>Mechanical Problems of novel Back Contact Solar Modules</b> .....	464
<i>S. Wiese, F. Kraemer, E. Peter, J. Seib</i>	
<b>Wafer Level System Packaging and Integration for Solid State Lighting (SSL)</b> .....	470
<i>Xuejun Fan</i>	
<b>In-situ Moisture Desorption Characterization of Epoxy Mold Compound</b> .....	476
<i>Xuejun Fan, Vishal Nagaraj</i>	
<b>Fracture Toughness Characterization and Modeling of Interfaces in Microelectronic Packages - A Status Review</b> .....	482
<i>H. Pape, I. Maus, I. Paul, L. J. Ernst, B. Wunderle</i>	

<b>Multi-physics Simulation and Reliability Analysis for LED Luminaires under Step Stress Accelerated Degradation Test</b> .....	491
<i>Hongyu Tang, D. G. Yang, G. Q. Zhang, Fengze Hou, Miao Cai, Zaifu Cui</i>	
<b>Design of a 3-Axis Thermal Accelerometer Using an Electro-Thermo-Fluidic Model</b> .....	496
<i>L. A. Rocha, C. S. Silva, A. J. Pontes, J. C. Viana</i>	
<b>A Parametric Multilevel MEMS Simulation Methodology using Finite Element Method and Mesh Morphing</b> .....	500
<i>Vladimir A. Kolchuzhin, Jan E. Mehner</i>	
<b>Accelerated Testing Method of LED Luminaries</b> .....	505
<i>M. Cai, D. G. Yang, S. Koh, C. A. Yuan, W. B. Chen, B. Y. Wu, G. Q. Zhang</i>	
<b>A Multivariate Parameter Analysis of Copper Pillars Eases the Design of Denser Interconnects</b> .....	511
<i>Gerd Schlottig, Thomas Brunschwiler, Javier Goicochea, Werner Escher, Bruno Michel</i>	
<b>FEM Stress Analysis in BGA Components Subjected to JEDEC Drop Test Applying High Strain Rate Lead-Free Solder Material Models</b> .....	517
<i>Frank Kraemer, Karsten Meier, Steffen Wiese, Sven Rzepka</i>	
<b>Simulation and Qualification of a System-in-Package (SiP) based Solid State Lighting (SSL) Module</b> .....	524
<i>D. M. Farley, F. Boschman, J. E. Bullema, A. W. J. Gielen, P. Hesen</i>	
<b>3D Deformation FEM Simulations and Measurement during VDMOS Transistor Operation</b> .....	527
<i>E. Marcault, D. Weidmann, A. Bourennane, M. Breil, L. Charpiot</i>	
<b>Sintering Process of Silver Nanoparticles in Ink-Jet Printed Conductive Microstructures - Molecular Dynamics Approach</b> .....	531
<i>Tomasz Fa-at, Bartosz P-atek, Jan Felba</i>	
<b>A Comparison Study of the Prognostics Approaches to Light Emitting Diodes under Accelerated Aging</b> .....	536
<i>Thamo Sutharssan, Chris Bailey, Stoyan Stoyanov</i>	
<b>The Method of Lines for the Analysis of Mechanical Structures</b> .....	544
<i>Amirali Taghavi, Larissa Vietzorreck</i>	
<b>Thermosonic Flip-chip Assembly on Flex Substrates</b> .....	549
<i>Guangbin Dou, Andrew S. Holmes</i>	
<b>Characterisation of Lead-free Solders at High Strain Rates Considering Microstructural Conditions</b> .....	554
<i>Karsten Meier, Frank Kraemer, Mike Roellig, Klaus-Juergen Wolter</i>	
<b>Cohesive Zone Model for Delamination Analysis of an Embedded Die System in Package</b> .....	564
<i>Xiaopei Li, Jianghai Gu, Yangjian Xu</i>	
<b>Investigation of Interface Delamination in a SO8 Package under Reflow</b> .....	574
<i>Yumin Liu, Yong Liu, Suresh Belani, Oseob Jeon</i>	
<b>Reliability Modeling of Electronic Systems Subjected to High Strain Rates</b> .....	580
<i>Pradeep Lall, Sandeep Shantaram, David Locker</i>	
<b>Interrogation of Thermo-Mechanical Damage in Field-Deployed Electronics</b> .....	597
<i>Pradeep Lall, Mahendra Harsha, Kai Goebel, Jim Jones</i>	
<b>Simulation of Diffusion Controlled Intermetallic Formation of Au/Al Interface</b> .....	613
<i>Rui Huang, Yik Yee Tan, Juergen Walter, Heinz Pape, Xuejun Fan, Heinrich Koerner</i>	
<b>Electro-Thermal Simulation of a Semiconductor Power Switch Considering Damage Effects</b> .....	620
<i>Ilko Schmadlak, Torsten Hauck</i>	
<b>Determination of Interface Fracture Parameters by Shear Testing Using Different Theoretical Approaches</b> .....	624
<i>R. Dudek, B. Bramer, J. Auersperg, R. Pufall, H. Walter, B. Seiler, B. Wunderle</i>	
<b>Nonlinear Copper Behavior of TSV and the Cracking Risks during BEoL-Built-up for 3D-IC-Integration</b> .....	634
<i>J. Auersperg, D. Vogel, E. Auerswald, S. Rzepka, B. Michel</i>	
<b>Measurement and Simulation of Moisture Effects on Electromagnetic Radiation of Printed Circuit Boards</b> .....	640
<i>H. Fridhi, G. Duchamp, V. Vigneras, A. Guedon-Gracia, J. Y. Deletage, H. Fremont</i>	
<b>Nonlinear Analyses of Semi-Embedded Through-Silicon Via (TSV) Interposer with Stress Relief Gap Under Thermal Operating and Environmental Conditions</b> .....	645
<i>John H. Lau, Shang-Tsai Wu, Heng-Chieh Chien</i>	
<b>Thermal-Mechanical Responses of 3D IC Integration with a Passive TSV Interposer</b> .....	651
<i>John H. Lau, Shang-Tsai Wu, Heng-Chieh Chien</i>	
<b>Numerical and Experimental Results Correlation during Power MOSFET Ageing</b> .....	659
<i>T. Azoui, P. Tounsi, Ph. Dupuy, J. M. Dorkel, D. Martineau</i>	
<b>Failure Modeling of BGA Package for Reliability Evaluation of Handheld Products under Drop Event</b> .....	663
<i>Soonwan Chung, Jae Kwak, Seunghee Oh, Changsun Kang</i>	

<b>Simulation-based Prediction of Reliability and Robustness of Interconnect Systems for Semiconductor Applications</b> .....	669
<i>M. Ackermann, V. Hein, K. Weide-Zaage</i>	
<b>Finite Element Modeling of Solder Joint Fatigue in Four-Point Bending Test</b> .....	674
<i>Baris Sabuncuoğlu, Filip Vanhee, Geert Willems, Bart Vandeveld, Dirk Vandepitte, Ingrid De Wolf</i>	
<b>Mechanical and Tribological Characterizations for Reliability Design of Micromembranes</b> .....	681
<i>Marius Pustan, Corina Birleanu, Cristian Dudescu, Ovidiu Belcin</i>	
<b>Consistent Analytical Model for Single and Dual Thickness Capacitive Micromachined Ultrasound Transducers (cMUT)</b> .....	687
<i>X. Rottenberg, A. Erismis, P. Czarnecki, H. A. C. Tilmans</i>	
<b>Studies on the Transitional Behaviors of Au-to-Au Micro-contact during the Initialization Stage of Contact Formation under Low Contact Force</b> .....	693
<i>Haodong Qiu, Hong Wang, Feixiang Ke</i>	
<b>A Cost-effective Active Cooling Method: Thermal Performance and Cost Analysis</b> .....	698
<i>Sheng Liu, Ling Xu, Mingxiang Chen</i>	
<b>Thermal and Moisture Degradation in SSL System</b> .....	702
<i>Sau Koh, Willem V. D. Driel, G. Q. Zhang</i>	
<b>Characterization of Adhesives and Interface Strength for Automotive Applications</b> .....	708
<i>B. Ozturk, P. Gromala, C. Otto, A. Fischer, K. M. B. Jansen, L. J. Ernst</i>	
<b>Polymer-based 2D/3D Wafer Level Heterogeneous Integration for SSL Module</b> .....	712
<i>Cadmus Yuan, Jia Wei, Huaiyu Ye, Sau Koh, Stephen Harianto, Monique Van Den Nieuwenhof</i>	
<b>Thermal Challenges in Photonic Integrated Circuits</b> .....	719
<i>Jeff Punch</i>	
<b>Experimental Assessment of Flat-type Photovoltaic Module Thermal Behavior</b> .....	725
<i>Shrinivas Bojanampati, Peter Rodgers, Valerie Evelyn</i>	
<b>Evaluation of Adhesion Strength of Semiconductor Package with the Weibull Stress</b> .....	729
<i>Eigo Matsuura, Kanako Sawada, Hideko Mukaida, Hideo Aoki, Fumiyoshi Minami</i>	
<b>Trends and Challenges in Lead Free Soldering</b> .....	734
<i>Dias Lopes, Margarida Pinto, Eurico Assuncao, Luisa Coutinho</i>	
<b>Author Index</b>	